## FL850-03-80 High Power type LED

FL850-03-80 is an AlGaAs LED mounted on a lead frame and molded with super beam lens. On forward bias, it emits a band of visible light which peaks 850nm.

These devices are intended to be operated at pulsed current of 4A under maximum 4.5V for stable long life. 

Outer dimension (Unit: mm)

◆Specifications

1) Product Name Super Flux mold type LED

2) Type No. FL850-03-80

3) Chip

(1) Chip Material GaAlAs

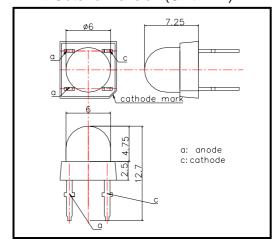
(2) Chip Dimension 800um\*800um

(3) Peak Wavelength 850nm typ.

4) Package

(1) Type Super Beam type LED

(2) Resin Material Epoxy Resin(3) Lead Frame Soldered



## ♦ Absolute Maximum Ratings

Item	Symbol	Maximum Rated Value	Unit	Ambient Temperature	
Power Dissipation	Pp	310 mW		Ta=25°C	
Forward Current	lF	200	mΑ	Ta=25°C	
Pulse Forward Current	lfp	4000	mΑ	Ta=25°C	
Reverse Voltage	Vr	10	V	Ta=25°C	
Operating Temperature	Topr	-30 ~ +85	°C		
Storage Temperature	Tstg	-30 ~ +100	°C		
Soldering Temperature	TsoL	260	°C		

<sup>‡</sup>Pulse Forward Current condition: Duty=1% and Pulse Width=10us.

## ◆Electro-Optical Characteristics [Ta=25°C]

Item	Symbol	Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	VF	IF=100mA		1.4	1.5	V
Pulsed Forward Voltage	VF	IFP=4A		3.3	4.5	V
Reverse Current	lr	Vr=10V			10	uA
Total Radiated Power	Po	IF=100mA	35.0	60.0		mW
Radiant Intensity	ΙE	IF=100mA		230		mW/sr
Peak Wavelength	λР	Ir=50mA	840	850	860	nm
Half Width	Δλ	Ir=50mA		40		nm
Viewing Half Angle	θ 1/2	IF=50mA		±8		deg.
Rise Time	tr	Ir=50mA		15		ns
Fall Time	tf	Ir=50mA		10		ns

<sup>‡</sup>Total Radiated Power is measured by Photodyne #500

<sup>‡</sup>Soldering condition: Soldering condition must be completed within 3 seconds at 260°C

<sup>‡</sup>Radiant Intensity is measured by Tektronix J-6512.